



## Material Content Data Sheet



Sales Product Name	TLE8080EM			Issued		7. January 2020		
MA#	MA005413582							
Package	PG-SSOP-24-9			Weight*		150.89 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	3.456	2.29	2.29	22902	22902
leadframe	inorganic material	phosphorus	7723-14-0	0.017	0.01		111	
	non noble metal	zinc	7440-66-6	0.067	0.04		446	
	non noble metal	iron	7439-89-6	1.345	0.89		8914	
	non noble metal	copper	7440-50-8	54.617	36.20	37.14	361962	371433
wire	non noble metal	copper	7440-50-8	0.867	0.57	0.57	5749	5749
encapsulation	organic material	carbon black	1333-86-4	0.173	0.11		1145	
	plastics	epoxy resin	-	7.946	5.27		52659	
	inorganic material	silicondioxide	60676-86-0	78.249	51.86	57.24	518576	572380
leadfinish	non noble metal	tin	7440-31-5	2.911	1.93	1.93	19291	19291
plating	noble metal	silver	7440-22-4	0.234	0.16	0.16	1553	1553
glue	plastics	epoxy resin	-	0.252	0.17		1673	
	noble metal	silver	7440-22-4	0.757	0.50	0.67	5019	6692
*deviation	< 10%	Sum in total:			100.00		1000000	

### Important Remarks:

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This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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